Layer Name	Туре	Material	Thickness (mm)	Color	Epsilon R	Loss Tangent
F.Silkscreen	Top Silk Screen	Not specified	0 mm	White	1	0
F.Paste	Top Solder Paste		0 mm		1	0
F.Mask	Top Solder Mask	Not specified	0.06 mm	Black	3.3	0
F.Cu	copper		0.035 mm		1	0
Dielectric	prepreg	FR4	0.22 mm	FR4 natural	4.5	0.02
In1.Cu	copper		0.017 mm		1	0
Dielectric	core	FR4	0.41 mm	FR4 natural	4.5	0.02
In2.Cu	copper		0.017 mm		1	0
Dielectric	core	FR4	0.22 mm	FR4 natural	4.5	0.02
B.Cu	copper		0.035 mm		1	0
B.Mask	Bottom Solder Mask	Not specified	0.06 mm	Black	3.3	0
B.Paste	Bottom Solder Paste		0 mm		1	0
B.Silkscreen	Bottom Silk Screen	Not specified	0 mm	White	1	0

BOARD CHARACTERISTICS

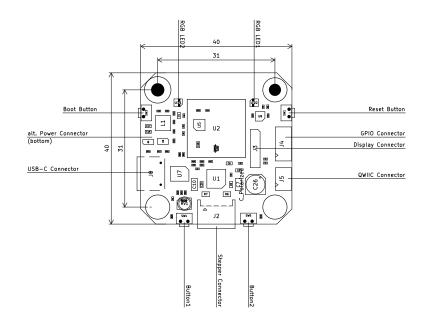
Copper Layer Count: 4 Board Thickness: 1.074 mm

Board overall dimensions: 40 mm x 40 mm

Min track/spacing: 0.125 mm / 0.125 mm Min hole diameter: 0.2 mm

Copper Finish: ENIG Impedance Control: No Castellated pads: No Plated Board Edge: No

Edge card connectors: No



Project: https://github.com/nerdyscout/esp32stepper
License: https://ohwr.org/cern_ohl_w_v2.txt (CERN-OHL-W)

DE000152

Stefan Herold

Sheet:

File: esp32stepper.kicad_pcb

Title: ESP32	SIEPPER
Size: A4	Date: 2025-06-27

 Size: A4
 Date: 2025-06-27
 Rev: 1.0

 KiCad E.D.A. 9.0.1
 Id: 1/1

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